

FL2002

No Clean Liquid Flux



Product Description

Hasaconi FL2002 is a low residue, no clean rosin mildly activated (RMA) flux. Presence of low halides in the flux aids the cleaning process without causing corrosion to the printed circuit boards. This flux has been formulated such that no solder balls are formed and bridging problems are completely eliminated. The flux leaves a very thin transparent coat, which not only protects the board surface but also gives it additional aesthetic values.

Application

FL2002 is specially formulated for spraying and foaming process and can also be used in dipping applications. Recommended onboard preheat temperature is 90 – 110 °C.

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Recommended Solvent

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, FL2002 can be stored for up to 6 months. FL2002 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 18kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Light yellow
Specific Gravity @ 25°C	0.799 +/- 0.005
JIS Z 3197 8.2.2	
Non-volatile Solid Content (110°C, 1hr)	7.0 +/- 0.5 wt%
IPC-TM-650 2.3.34	
JIS Z 3197 8.1.3	
Halide Content	0.08 +/- 0.01 wt%
JIS Z 3197 8.1.4.2.1	
Acid Value Test KOH/g flux	18.0 +/- 1.0 mg
IPC-TM-650 2.3.13	
JIS Z 3197 8.1.4.1	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
JIS Z 3197 8.1.1	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 ⁸ Ω, Pass
IPC-TM-650 2.6.3.3	
JIS Z 3197 8.5.3	
Electromigration (85°C, 88.5%RH, 596hrs)	> 1 x 10 ¹¹ Ω, Pass
IPC-TM-650 2.6.14.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
Copper Mirror Test	Classified as "M", Pass
IPC-TM-650 2.3.32	
JIS Z 3197 8.4.2	
Flux Activity Classification	ROM1
IPC J-STD-004	
Spread Factor	> 85% (SnPb)
JIS Z 3197 8.3.1.1	
Residue Dryness Test	Dry
IPC-TM-650 2.4.47	
JIS Z 3197 8.5.1	
Surface Finish	Shiny

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